



Material Content Data Sheet



Sales Product Name	TLE7273-2E V50			Issued		11. December 2019		
MA#	MA003438458							
Package	PG-SSOP-14-2			Weight*		83.35 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.362	2.83	2.83	28338	28338
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8267	
	non noble metal	copper	7440-50-8	27.978	33.57	34.45	335682	344465
wire	noble metal	gold	7440-57-5	0.171	0.20	0.20	2046	2046
encapsulation	organic material	carbon black	1333-86-4	0.098	0.12		1176	
	plastics	epoxy resin	-	4.510	5.41		54118	
	inorganic material	silicondioxide	60676-86-0	44.418	53.30	58.83	532942	588236
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11712	11712
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9210	9210
glue	plastics	epoxy resin	-	0.333	0.40		3998	
	noble metal	silver	7440-22-4	1.000	1.20	1.60	11995	15993
*deviation	< 10%	Sum in total:			100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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